

Click [here](#) for the 3D model.

Dimensions	
Footprint	3528
L	3.5mm +/-0.2mm
W	2.8mm +/-0.2mm
H	1.1mm +/-0.1mm
S	0.8mm +/-0.3mm
F	2.2mm +/-0.1mm

Packaging Specifications	
Packaging	T&R, 330mm
Packaging Quantity	10000

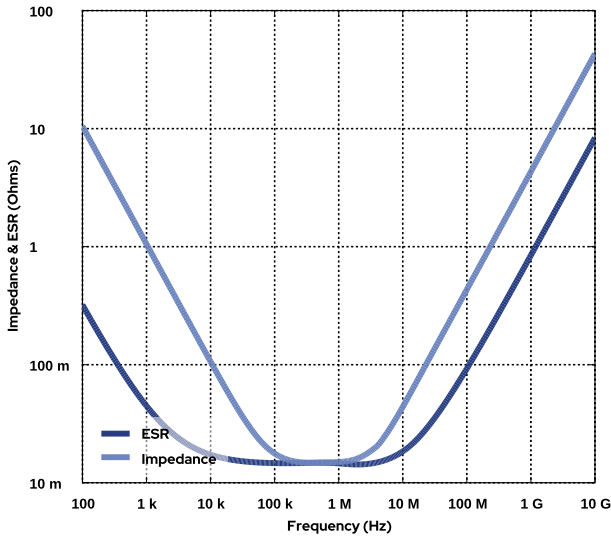
General Information	
Series	T523
Dielectric	Polymer Tantalum
Style	SMD Chip
Description	SMD, Polymer, Molded, Face Down Terminals
Features	Face Down
RoHS	Yes
Termination	Nickel Palladium Gold
AEC-Q200	No
Typical Component Weight	54.84 mg
Shelf Life	52 Weeks
MSL	3

Specifications	
Capacitance	150 uF
Capacitance Tolerance	20%
Voltage DC	6.3 VDC (105C)
Temperature Range	-55/+105°C
Rated Temperature	105°C
Life	2000 Hrs (105C)
Humidity	60C, 90% RH, 500 Hours, No Load
Dissipation Factor	8% 120Hz 25C
Failure Rate	N/A
ESR	30 mOhms (100kHz 25C)
Ripple Current	1870 mA (rms, 100kHz 45C), 1309 mA (rms, 85C), 467.5 mA (rms, 105C)
Leakage Current	94.5 uA (5min 25°C)

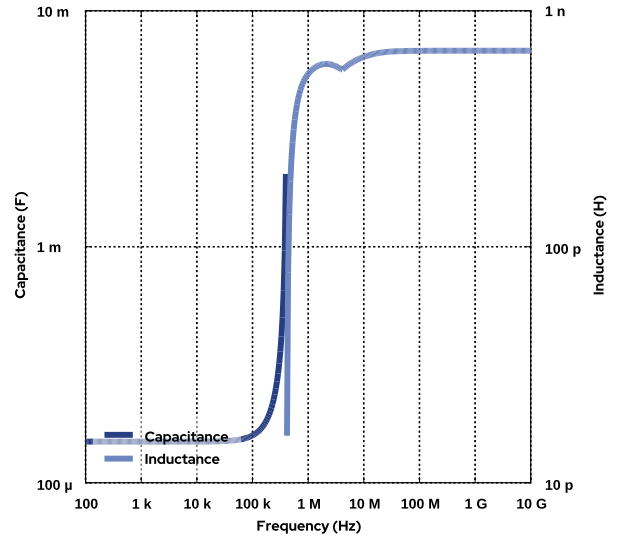
Simulations

For the complete simulation environment please visit [K-SIM](#).

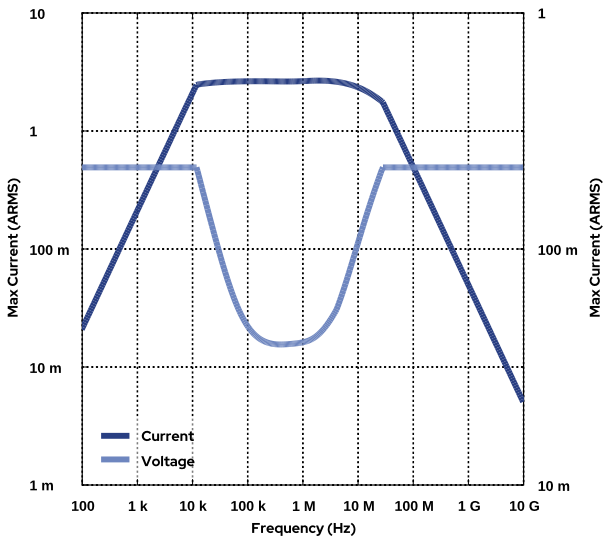
Impedance and ESR



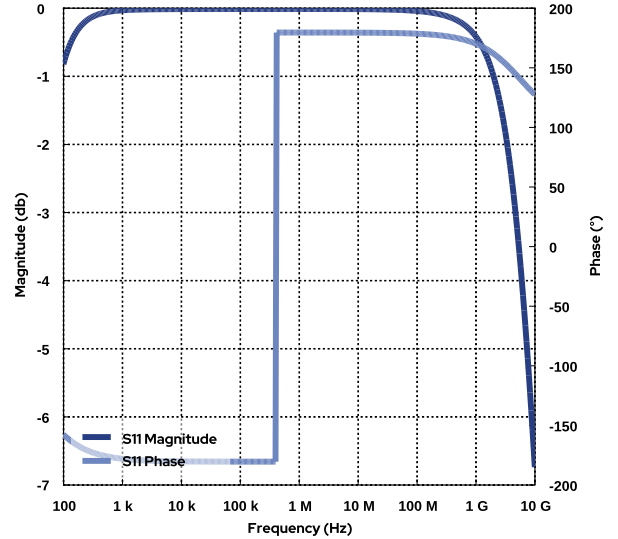
Capacitance and Inductance



Current and Voltage



S11

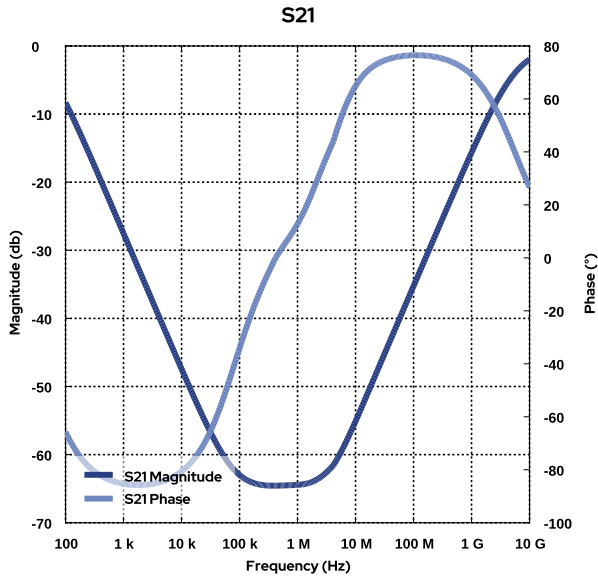




a YAGEO company

T523T157M006APE0307280

T523, Tantalum, Polymer Tantalum, Reduced Volume, 150 uF, 20%, 6.3 VDC, SMD, Polymer, Molded, Face Down Terminals, 30 mOhms, 3528, 1.2mm



These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance).
- The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other harmonics.
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.